



IMPORTANT NOTICE

10 December 2015

1. Global joint venture starts operations as WeEn Semiconductors

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As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

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Thank you for your cooperation and understanding,

WeEn Semiconductors





BYV10-600P

Ultrafast power diode

3 January 2014

Product data sheet

1. General description

Ultrafast power diode in a SOD59 (2-lead TO-220AC) plastic package.

2. Features and benefits

- Fast switching
- Low leakage current
- Low forward voltage drop
- Low thermal resistance
- Soft recovery characteristic

3. Applications

- High frequency switched-mode power supplies
- Discontinuous Current Mode (DCM) Power Factor Correction (PFC)

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	-	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $T_{mb} \leq 109$ °C; square-wave pulse; Fig. 1 ; Fig. 2 ; Fig. 3	-	-	10	A
Static characteristics						
V_F	forward voltage	$I_F = 10$ A; $T_j = 150$ °C; Fig. 6	-	-	1.6	V
Dynamic characteristics						
t_{rr}	reverse recovery time	$I_F = 1$ A; $V_R = 30$ V; $dI_F/dt = 100$ A/ μ s; $T_j = 25$ °C; Fig. 7	-	20	-	ns

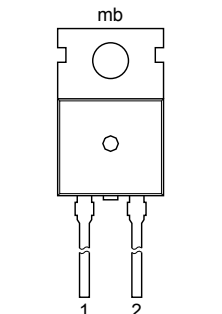
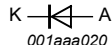


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5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p>TO-220AC (SOD59)</p>	
2	A	anode		
mb	mb	mounting base; connected to cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYV10-600P	TO-220AC	plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC	SOD59

7. Marking

Table 4. Marking codes

Type number	Marking code
BYV10-600P	BYV10-600P

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	600	V
V_{RWM}	crest working reverse voltage		-	600	V
V_R	reverse voltage	DC	-	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $T_{mb} \leq 109\text{ }^\circ\text{C}$; square-wave pulse; Fig. 1 ; Fig. 2 ; Fig. 3	-	10	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{mb} \leq 109\text{ }^\circ\text{C}$; square-wave pulse	-	20	A

Symbol	Parameter	Conditions	Min	Max	Unit
I _{FSM}	non-repetitive peak forward current	t _p = 10 ms; T _{j(initial)} = 25 °C; sine-wave pulse; Fig. 4	-	80	A
		t _p = 8.3 ms; T _{j(initial)} = 25 °C; sine-wave pulse; Fig. 4	-	88	A
T _{stg}	storage temperature		-65	175	°C
T _j	junction temperature		-	175	°C

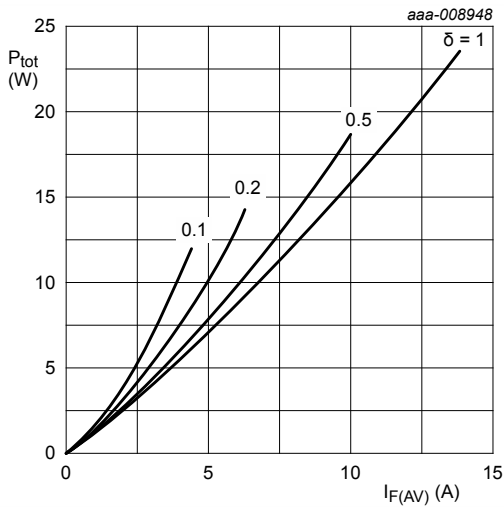


Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_O = 1.268 \text{ V}; R_S = 0.031 \text{ } \Omega$$

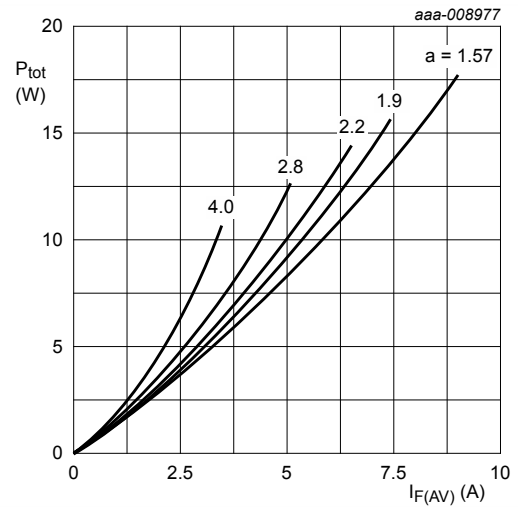


Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

$$V_O = 1.268 \text{ V}; R_S = 0.031 \text{ } \Omega$$

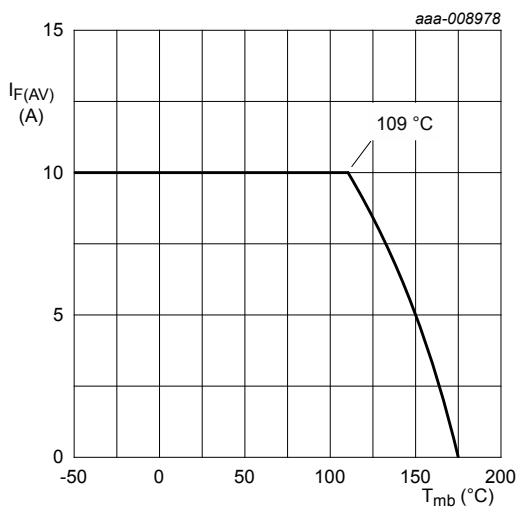


Fig. 3. Forward current as a function of mounting base temperature; maximum values

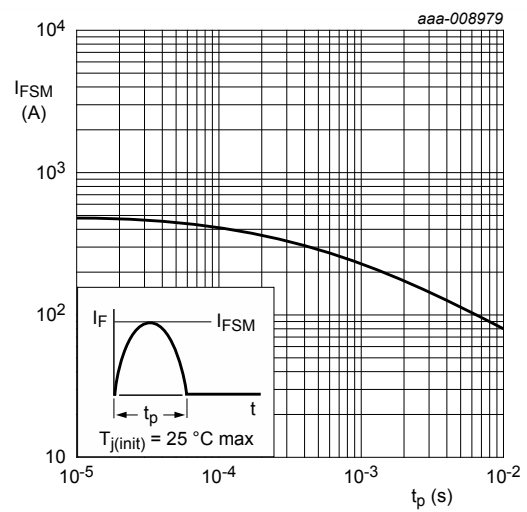


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	-	3.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	60	-	K/W

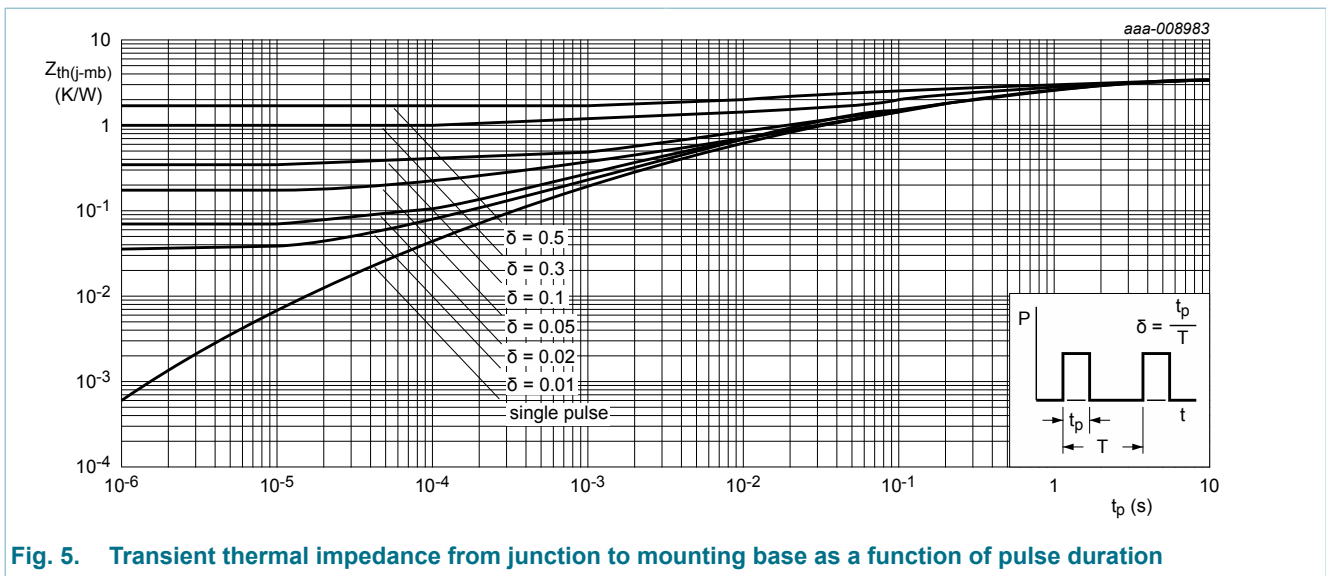


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V_F	forward voltage	$I_F = 10\text{ A}; T_j = 25\text{ °C};$ Fig. 6	-	1.5	2	V
		$I_F = 10\text{ A}; T_j = 150\text{ °C};$ Fig. 6	-	-	1.6	V
I_R	reverse current	$V_R = 600\text{ V}; T_j = 25\text{ °C}$	-	-	10	μA
		$V_R = 500\text{ V}; T_j = 150\text{ °C}$	-	-	250	μA
Dynamic characteristics						
t_{rr}	reverse recovery time	$I_F = 1\text{ A}; V_R = 30\text{ V}; dI_F/dt = 50\text{ A}/\mu\text{s}; T_j = 25\text{ °C};$ Fig. 7	-	35	50	ns
		$I_F = 1\text{ A}; V_R = 30\text{ V}; dI_F/dt = 100\text{ A}/\mu\text{s}; T_j = 25\text{ °C};$ Fig. 7	-	20	-	ns

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
		$I_F = 10 \text{ A}$; $V_R = 200 \text{ V}$; $di_F/dt = 200 \text{ A}/\mu\text{s}$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 7	-	40	-	ns

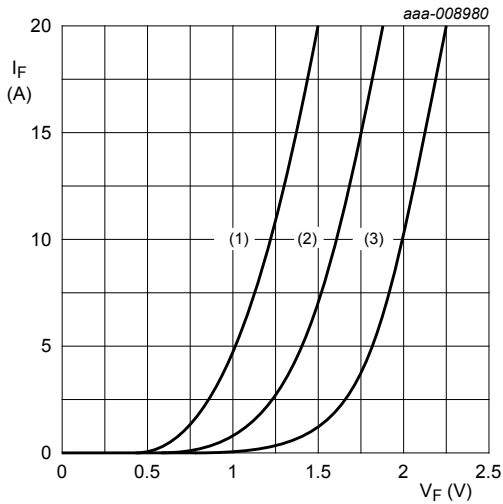


Fig. 6. Forward current as a function of forward voltage

- (1) $T_j = 150 \text{ }^\circ\text{C}$; typical values;
 - (2) $T_j = 150 \text{ }^\circ\text{C}$; maximum values;
 - (3) $T_j = 25 \text{ }^\circ\text{C}$; maximum values;
- $V_O = 1.268 \text{ V}$; $R_S = 0.031 \text{ } \Omega$

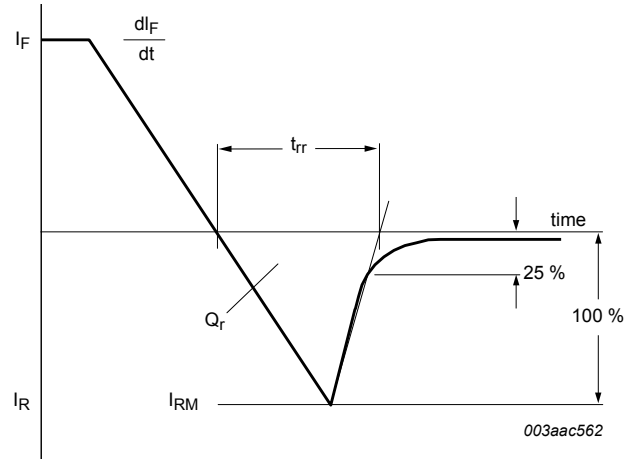


Fig. 7. Reverse recovery definitions; ramp recovery

11. Package outline

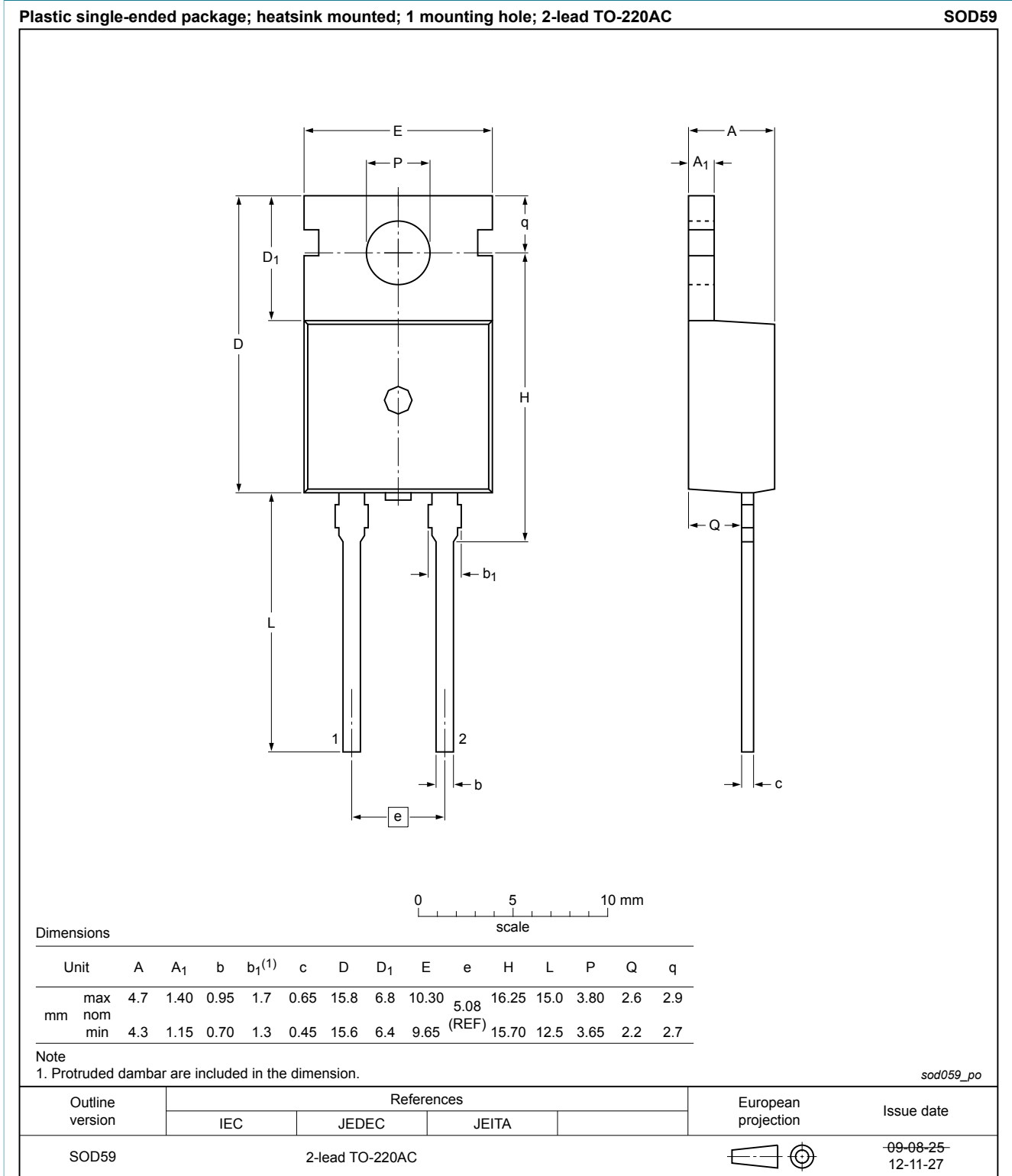


Fig. 8. Package outline TO-220AC (SOD59)

12. Legal information

12.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 3 January 2014